

## General Description

The WSD2045DN22 is the highest performance trench N-Ch and P-Channel MOSFETs with extreme high cell density , which provide excellent  $R_{DS(ON)}$  and gate charge for most of the small power switching and load switch applications.

The WSD2045DN22 meet the RoHS and Green Product requirement with full function reliability approved.

## Features

- 100% UIS +  $R_g$  Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

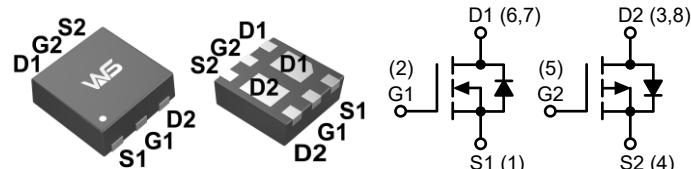
## Product Summery

$BV_{DSS}$	$R_{DS(ON)}$	$I_D$
20V	20mΩ	10A
-20V	48mΩ	-8A

## Applications

- Load Switch.
- Networking.

## DFN2X2-6S Pin Configuration



## Absolute Maximum Ratings ( $T_A=25^\circ C$ , Unless Otherwise Noted)

Symbol	Parameter	Rating		Units	
		N-Channel	P-Channel		
$V_{DS}$	Drain-Source Voltage	20	-20	V	
$V_{GS}$	Gate-Source Voltage	$\pm 12$	$\pm 12$		
$I_D$	Continuous Drain Current	$T_C=25^\circ C$	10	-8	A
$I_{DM}^1$	Pulse Drain Current	$T_C=25^\circ C$	30	-24	A
$E_{AS}^3$	Avalanche Energy, Single pulse	$L=0.5mH$	9	9	mJ
$I_{AS}^3$	Avalanche Current, Single pulse	$L=0.5mH$	6	-6	A
$P_D$	Power Dissipation	$T_C=25^\circ C$	16	17	W
		$T_C=70^\circ C$	9	10	
$R_{\theta JA}^2$	Thermal Resistance-Junction to Ambient	$t \leq 10s$	85	$^\circ C/W$	
		Steady State	135		
$T_{STG}$	Storage Temperature Range	-55 to 150		$^\circ C$	
$T_J$	Maximum Junction Temperature	150			

**N-Channel Electrical Characteristics ( $T_A=25^\circ\text{C}$ , Unless Otherwise Noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	20	---	---	V
$R_{\text{DS}(\text{ON})}^4$	Drain-Source On-state Resistance	$V_{\text{GS}}=4.5\text{V}$ , $I_D=4.5\text{A}$	---	20	24	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$ , $I_D=3.5\text{A}$	---	25	32	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	0.5	0.7	1.0	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=16\text{V}$ , $V_{\text{GS}}=0\text{V}$	---	---	1.0	$\mu\text{A}$
		$T_J=85^\circ\text{C}$	---	---	30	
$I_{\text{GSS}}$	Gate Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_G$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	---	2.2	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=4.5\text{V}$ , $I_{\text{DS}}=4.5\text{A}$	---	4.2	6.3	$\text{pC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	0.3	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	1.7	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=10\text{V}$ , $R_L=10\Omega$ , $I_{\text{DS}}=1\text{A}$ , $V_{\text{GEN}}=10\text{V}$ , $R_G=6\Omega$	---	2.4	---	ns
$T_r$	Turn-On Rise Time		---	13	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	15.5	---	
$T_f$	Turn-Off Fall Time		---	3	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	---	275	358	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	61	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	52	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$I_s$	Continuous Source Current	$T_C=25^\circ\text{C}$	---	---	10	A
$V_{\text{SD}}^4$	Diode Forward Voltage	$I_{\text{SD}}=1\text{A}$ , $V_{\text{GS}}=0\text{V}$	---	0.7	1.0	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_{\text{SD}}=4.5\text{A}$ , $dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	---	12.8	---	ns
	Reverse Recovery Charge		---	3.8	---	nC

Note:

1. Pulse width limited by max. junction temperature.
2. Surface mounted on  $1\text{in}^2$  pad area, steady state  $t = 999\text{s}$ .
3. UIS tested and pulse width limited by maximum junction temperature (initial temperature  $T_J=25^\circ\text{C}$ ).
4. Pulse test ; pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
5. Guaranteed by design, not subject to production testing.

**P-Channel Electrical Characteristics ( $T_A=25^\circ\text{C}$ , Unless Otherwise Noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=-250\mu\text{A}$	-20	---	---	V
$R_{\text{DS}(\text{ON})}^4$	Drain-Source On-state Resistance	$V_{\text{GS}}=-4.5\text{V}$ , $I_D=-2.5\text{A}$	---	48	56	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$ , $I_D=-2\text{A}$	---	66	78	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=-250\mu\text{A}$	-0.5	-0.7	-1.0	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-16\text{V}$ , $V_{\text{GS}}=0\text{V}$	---	---	-1.0	$\mu\text{A}$
		$T_J=85^\circ\text{C}$	---	---	-30	
$I_{\text{GSS}}$	Gate Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$R_G$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	---	10.8	---	$\Omega$
$Q_g$	Total Gate Charge	$V_{\text{DS}}=-10\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{DS}}=-2.5\text{A}$	---	4.6	---	$\text{pF}$
$Q_{\text{gs}}$	Gate-Source Charge		---	0.5	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	1.9	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time	$V_{\text{DD}}=-10\text{V}$ , $R_L=10\Omega$ , $I_{\text{DS}}=-1\text{A}$	---	6	---	$\text{ns}$
$T_r$	Turn-On Rise Time		---	14.4	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	26	---	
$T_f$	Turn-Off Fall Time		---	24	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-10\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1.0\text{MHz}$	---	365	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	75	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	60	---	

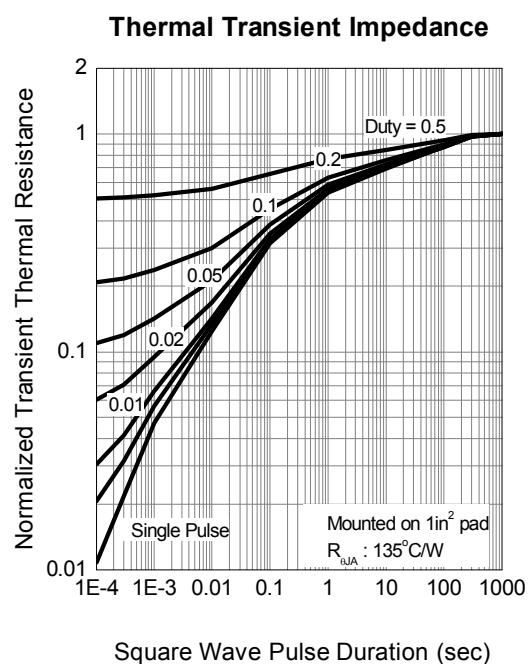
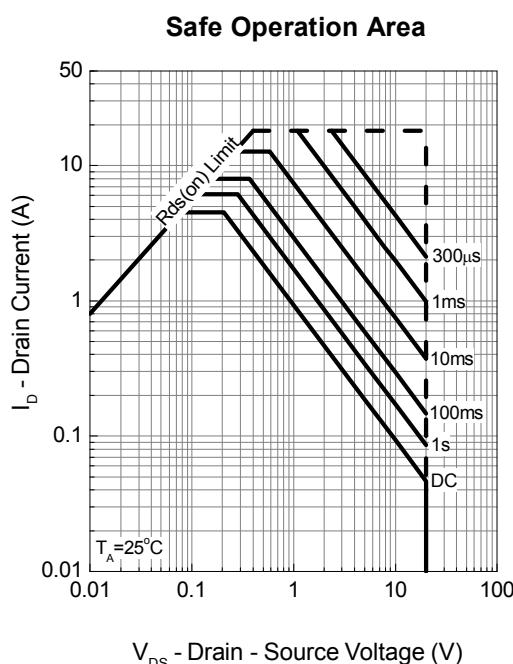
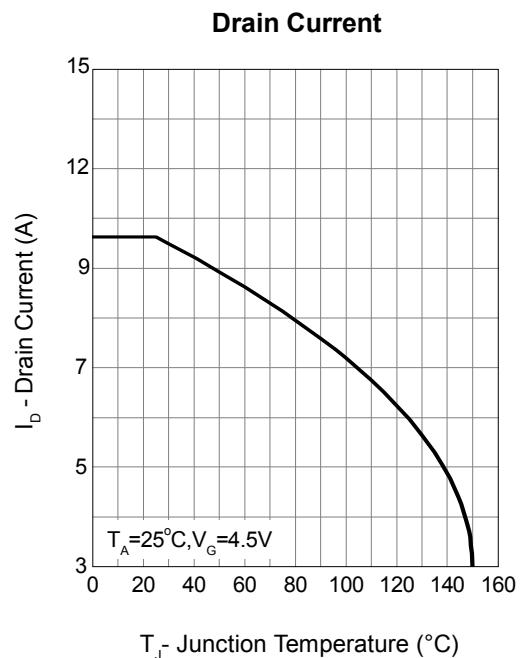
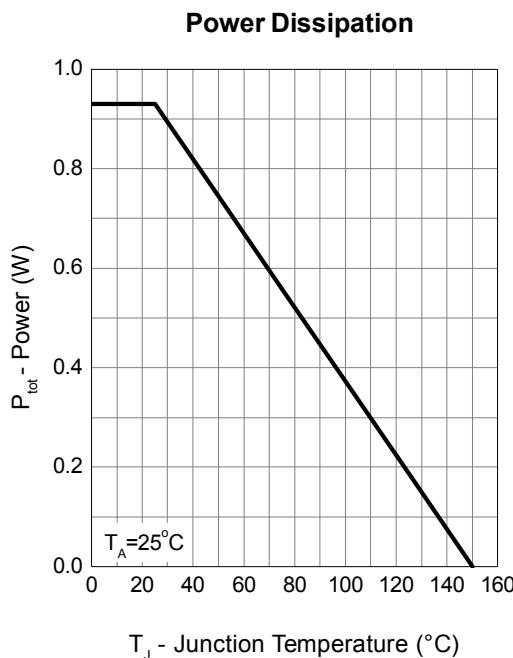
**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Units
$I_s$	Continuous Source Current	$T_c=25^\circ\text{C}$	---	---	-10	A
$V_{\text{SD}}^4$	Diode Forward Voltage	$I_{\text{SD}}=-1\text{A}$ , $V_{\text{GS}}=0\text{V}$	---	-0.8	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$I_{\text{SD}}=-2.5\text{A}$ , $dI_{\text{SD}}/dt=100\text{A}/\mu\text{s}$	---	22	---	ns
	Reverse Recovery Charge		---	6.0	---	nC

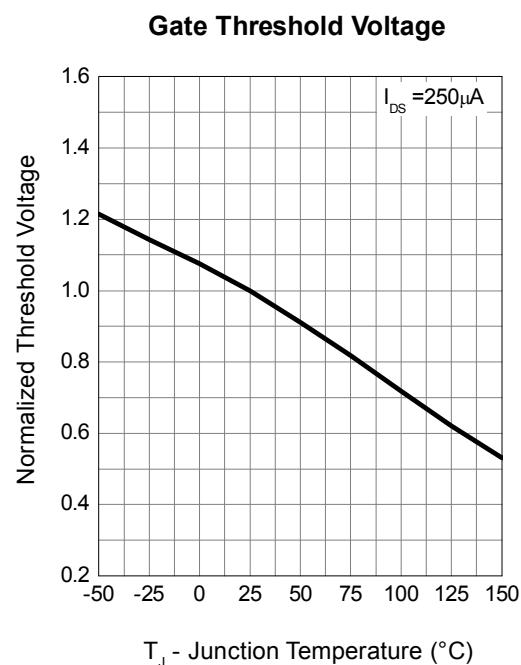
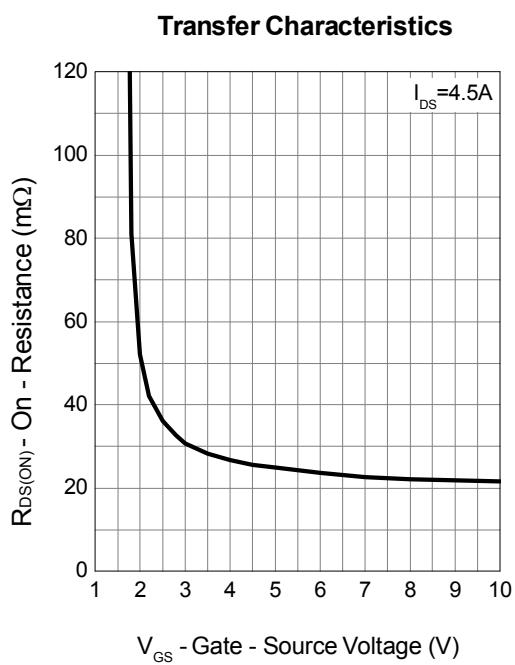
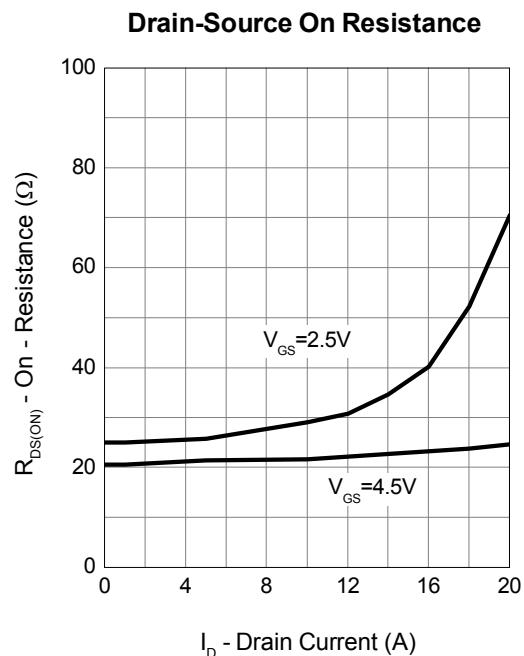
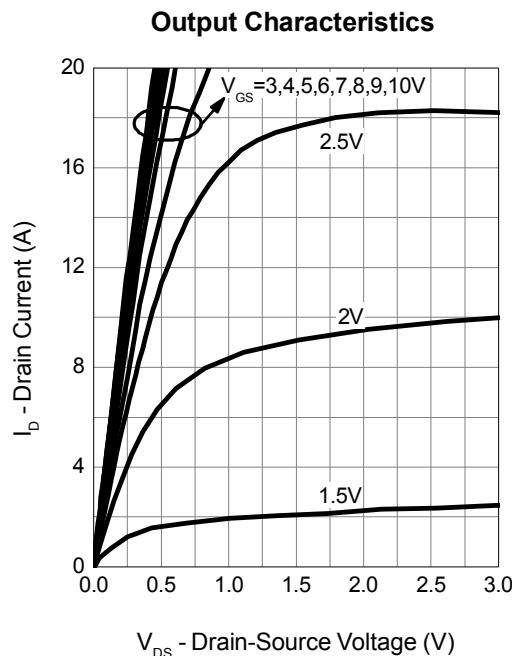
Note:

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5. Guaranteed by design, not subject to production testing.

### N-Channel Typical Characteristics

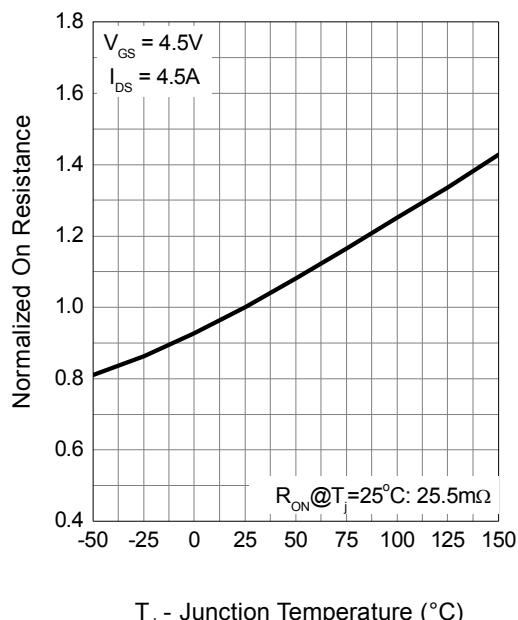


### N-Channel Typical Characteristics (Cont.)

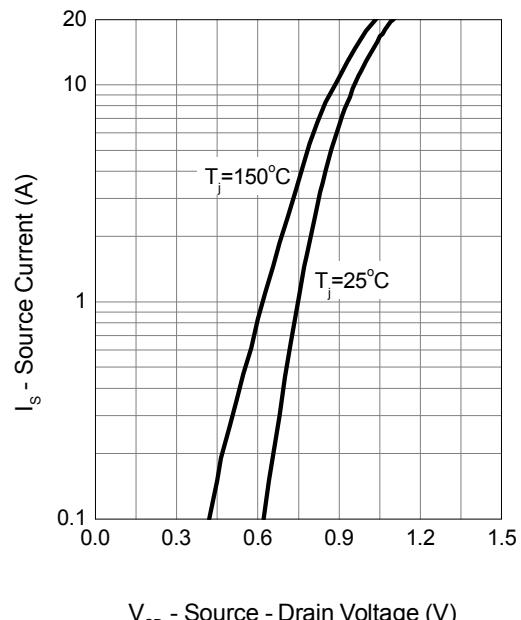


### N-Channel Typical Characteristics (Cont.)

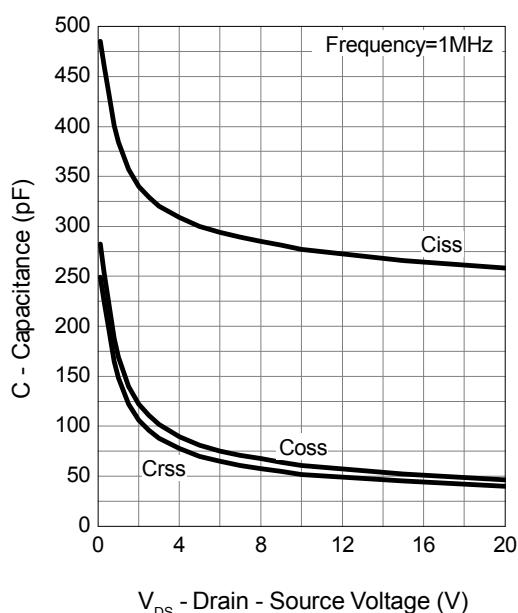
**Drain-Source On Resistance**



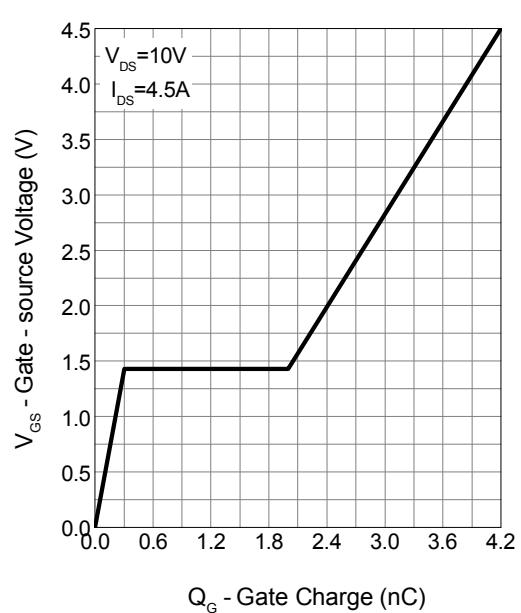
**Source-Drain Diode Forward**



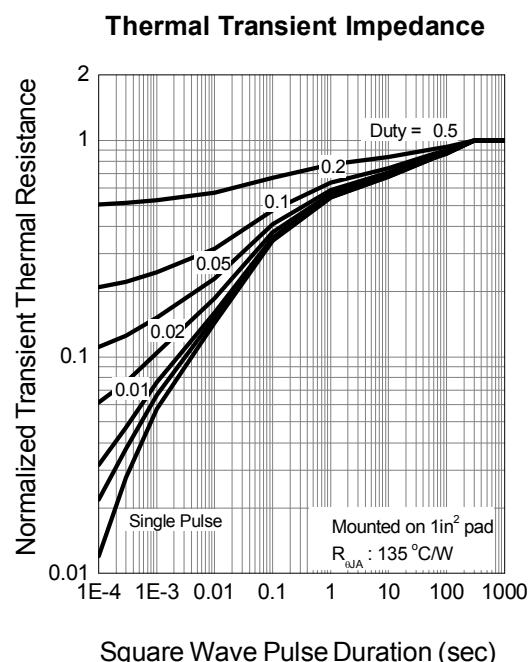
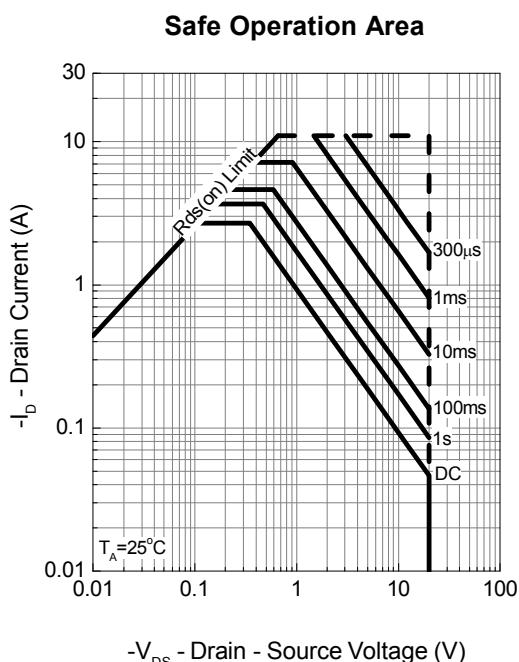
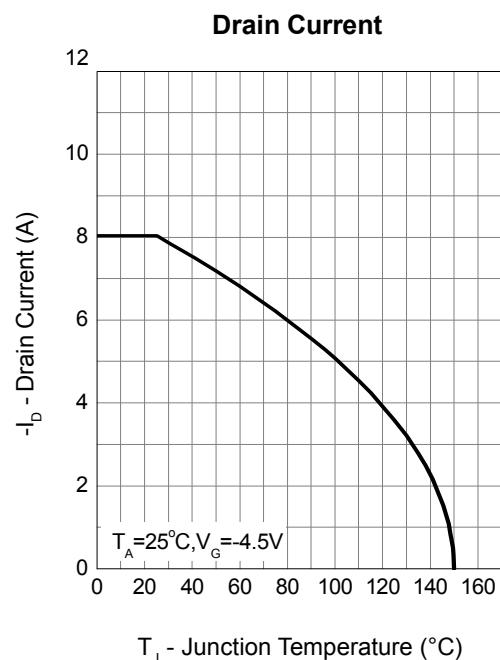
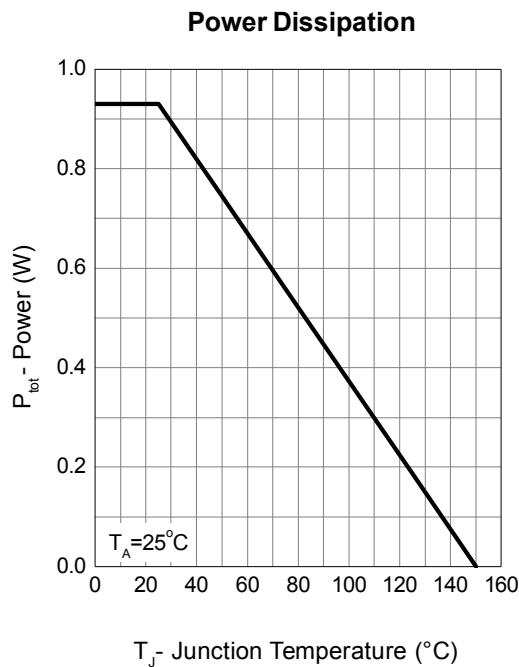
**Capacitance**



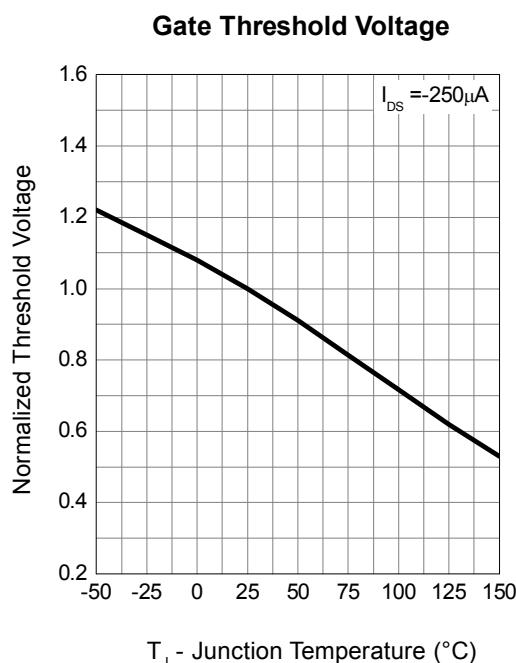
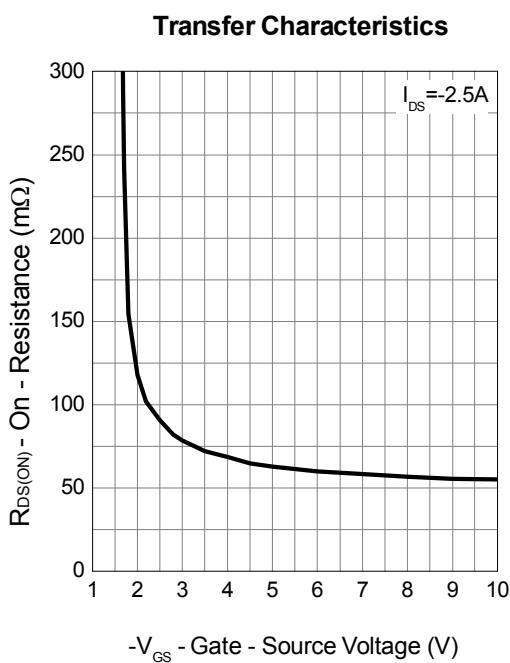
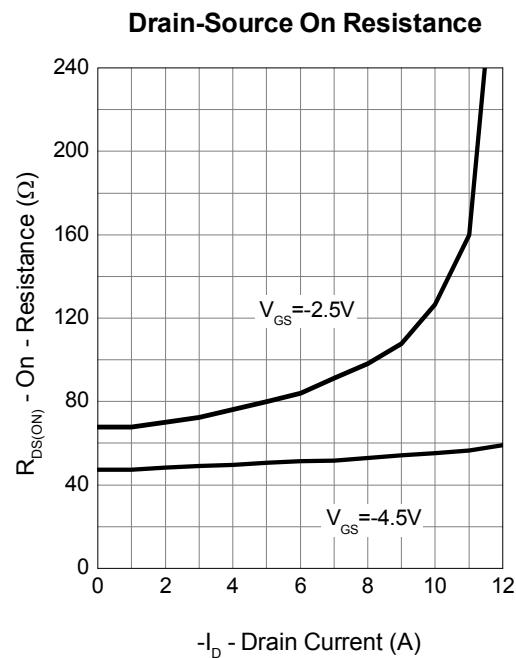
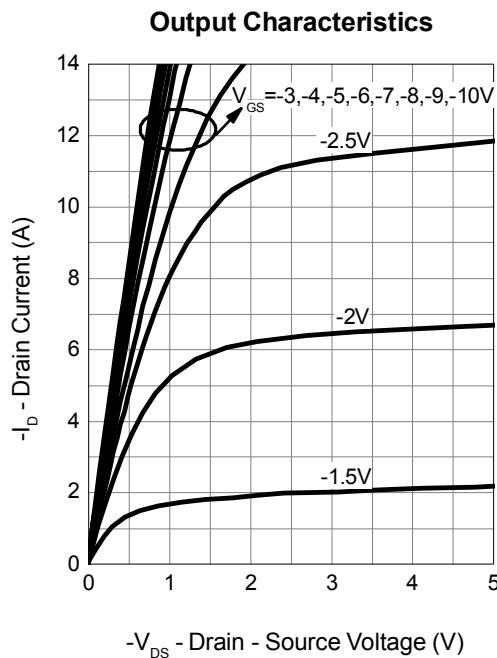
**Gate Charge**



## P-Channel Typical Characteristics

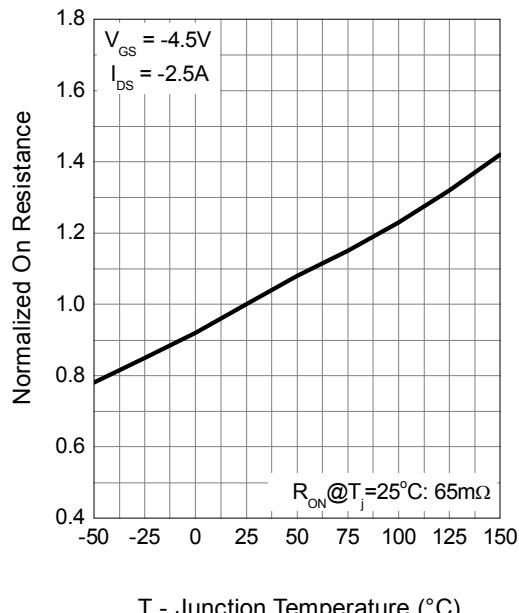


### P-Channel Typical Characteristics (Cont.)

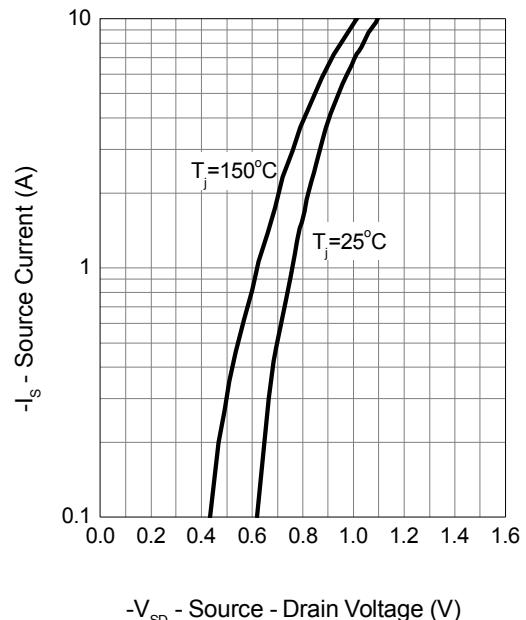


## P-Channel Typical Characteristics (Cont.)

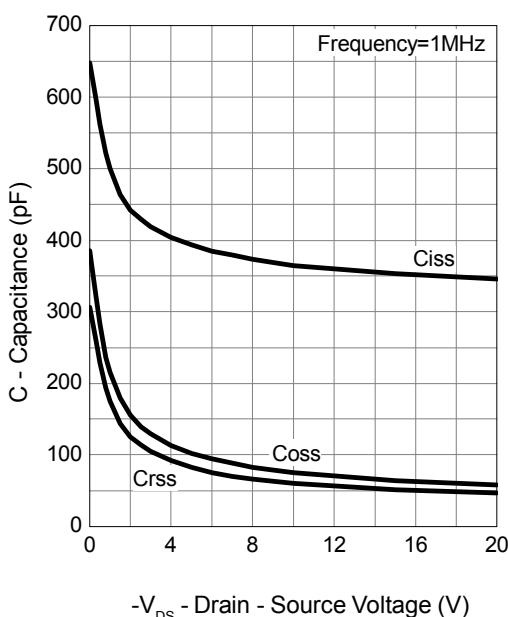
### Drain-Source On Resistance



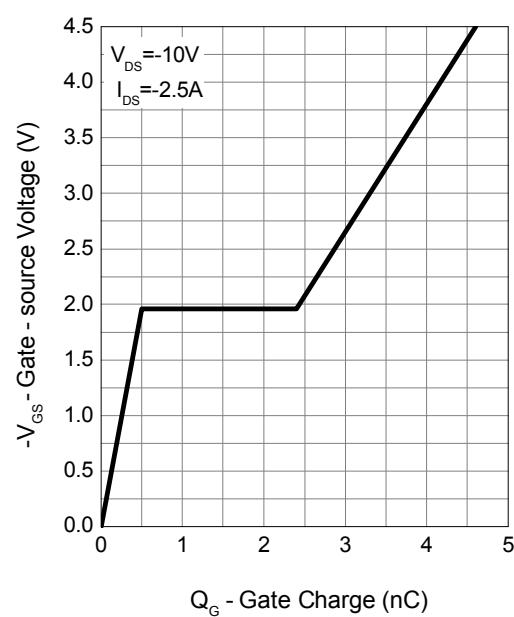
### Source-Drain Diode Forward



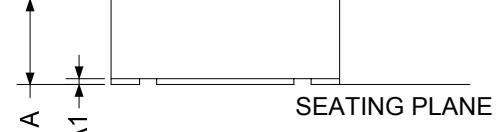
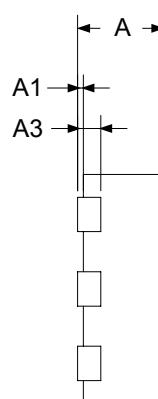
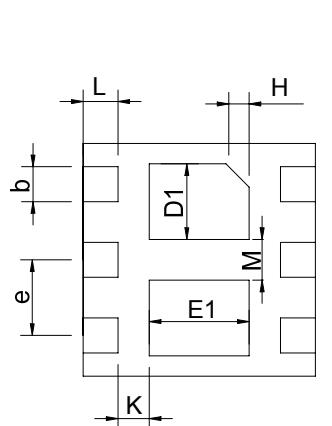
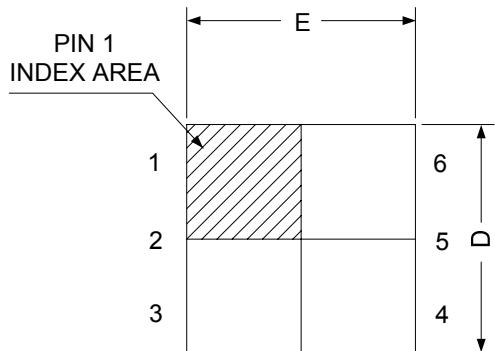
### Capacitance



### Gate Charge

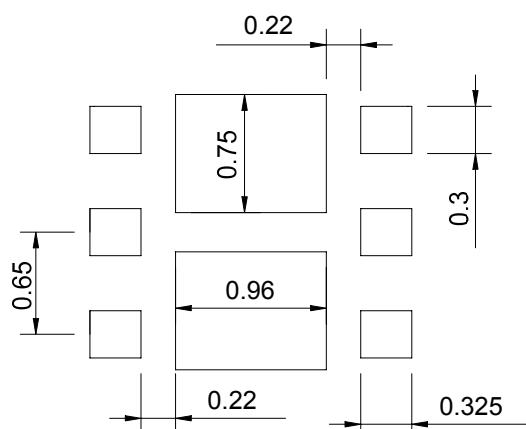


### Packaging information



SYMBOL	DFN2X2-6S			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.70	0.80	0.028	0.031
A1	0.00	0.05	0.000	0.002
A3	0.200 REF		0.008 REF	
b	0.25	0.35	0.010	0.014
D	1.90	2.10	0.075	0.083
D1	0.55	0.75	0.022	0.030
E	1.90	2.10	0.075	0.083
E1	0.76	0.96	0.030	0.038
e	0.65 BSC		0.026 BSC	
H	0.20 BSC		0.008 BSC	
K	0.17	0.37	0.007	0.015
L	0.25	0.35	0.010	0.014
M	0.25	0.45	0.010	0.018

### RECOMMENDED LAND PATTERN



UNIT: mm



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